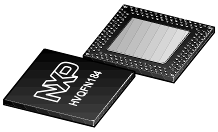


SOT1446-1

plastic thermal enhanced very thin quad flat package; no leads; 184 terminals; body 12 x 12 x 0.85 mm

3 June 2016

Package information

1. Package summary

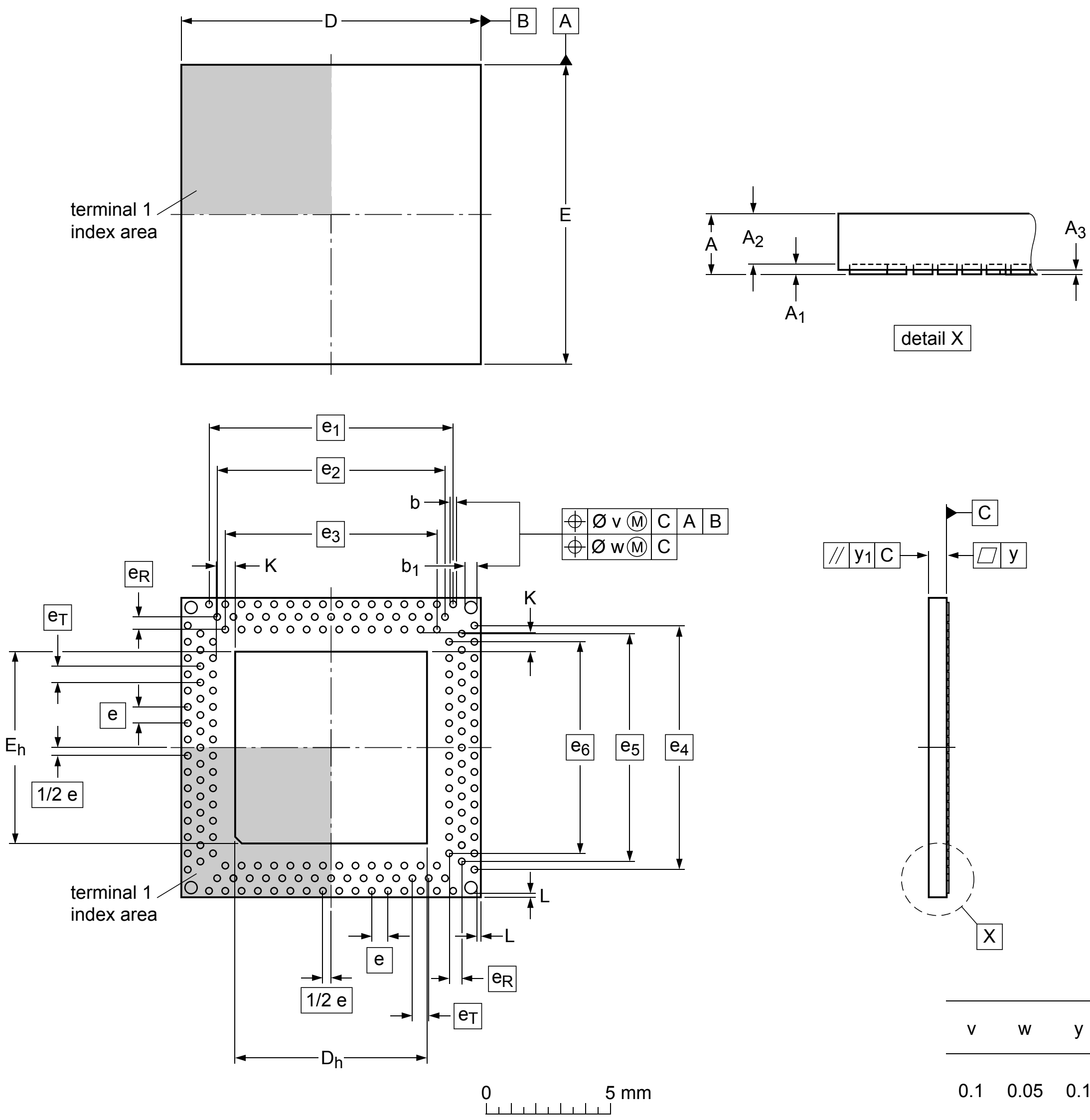
Terminal position code	B (bottom)
Package type descriptive code	HVQFN
Package type industry code	HVQFN184
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	29-7-2015

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		11.95	-	12	12.05	mm
E	package width		11.95	-	12	12.05	mm
A	seated height		-	-	-	0.85	mm
A_2	package height		0.64	-	0.675	0.71	mm
e	nominal pitch		-	-	0.65	-	mm
n_2	actual quantity of termination		-	-	184	-	

2. Package outline

HVQFN184: plastic thermal enhanced very thin quad flat package; no leads; 184 terminals; body 12 x 12 x 0.85 mm **SOT1446-1**



v	w	y	y_1
0.1	0.05	0.1	0.1

Dimensions (mm are the original dimensions)

Unit		A	A_1	A_2	A_3	b	b_1	$D^{(1)}$	D_h	$E^{(1)}$	E_h	e	e_1	e_2	e_3	e_4	e_5	e_6	e_T	e_R	K	L
	max	0.85	0.14	0.710	0.08	0.30	0.55	12.05	7.8	12.05	7.8										0.80	0.20
mm	nom		0.13	0.675	0.05	0.25	0.50	12.00	7.7	12.00	7.7	0.65	9.75	9.10	8.45	9.75	9.10	8.45	0.65	0.50	0.75	0.15
	min		0.12	0.640	0.02	0.20	0.45	11.95	7.6	11.95	7.6										0.70	0.10

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included

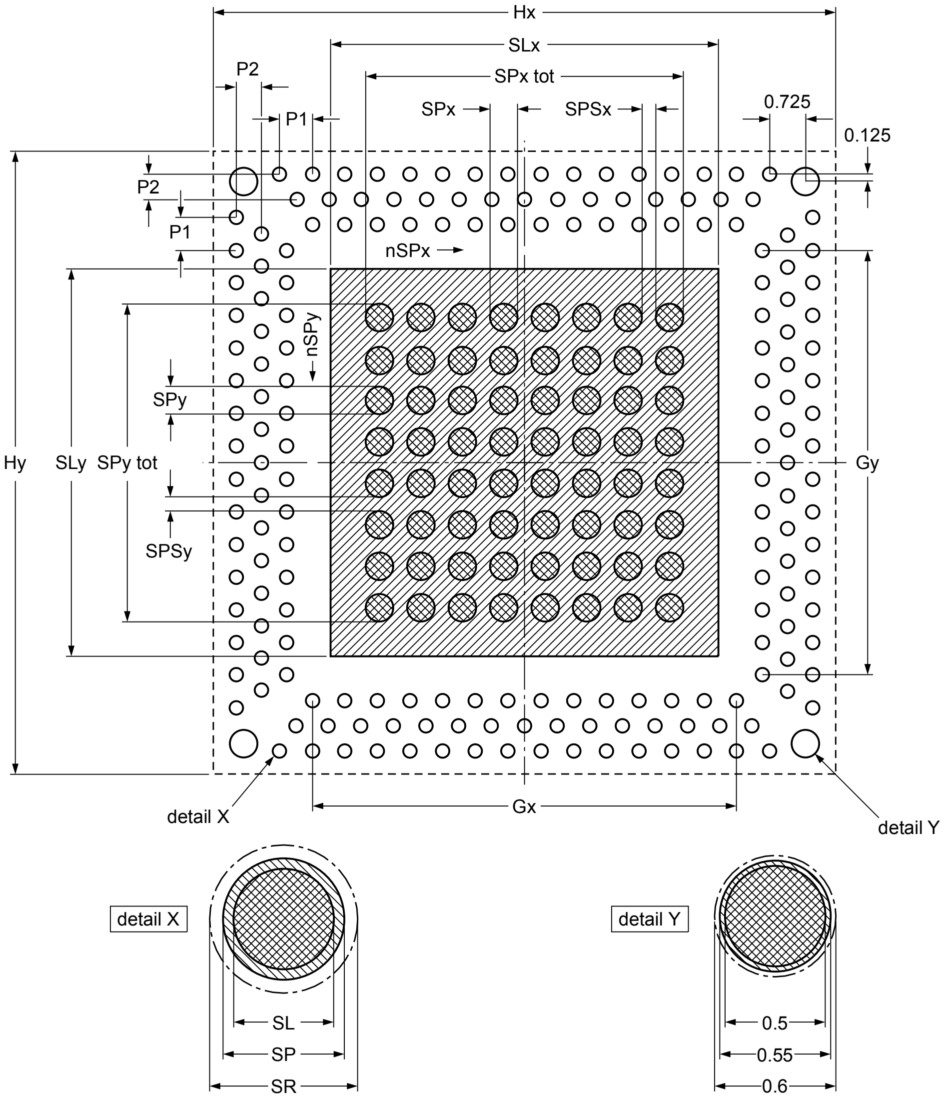
sot1446-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1446-1						~~15-04-20~~ 15-07-29

Fig. 1. Package outline HVQFN184 (SOT1446-1)

3. Soldering

Footprint information for reflow soldering of HVQFN184 package **SOT1446-1**



Recommended stencil thickness: 0.1 mm

▨ solder land ⬚ solder resist opening

▧ solder paste deposit ⬚ occupied area

Dimensions in mm

P1	P2	SL	SP	SR	SLx	SLy	SPx	SPy	SPx tot	SPy tot	SPSx	SPSy	nSPx	nSPy	Gx	Gy	Hx	Hy
0.65	0.50	0.25	0.30	0.37	7.70	7.70	0.55	0.55	6.29	6.29	0.27	0.27	8	8	8.45	8.45	12.4	12.4

Issue date ~~15-06-17~~
16-01-21

sot1446-1_fr

Fig. 2. Reflow soldering footprint for HVQFN184 (SOT1446-1)

4. Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

5. Contents

For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com
Date of release: 3 June 2016